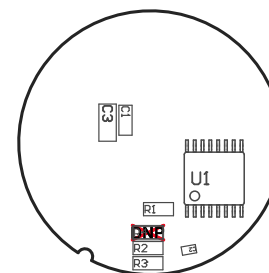


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: Do Not Populate

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01619	REV: E1	SUN REV: Not In VersionControl
	TID #: TIDA-01619		
PLOT NAME = Top Assembly Drawing	GENERATED : 2/19/2018	4:13:04 PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: Do Not Populate

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01619	REV: E1	SUN REV: Not In VersionControl
	TID #: TIDA-01619		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 2/19/2018 4:13:06 PM	TEXAS INSTRUMENTS	

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